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- (71) **Applicant:** ASTI HOLDINGS LIMITED [SG/SG];
Block 25 Kallang Avenue, #06-01, Kallang Basin Industrial Estate, Singapore 339416 (SG).
- (72) **Inventors:** AMANULLAH, Ajharali; Block 11, Pine Close, #12-107, Singapore 391011 (SG). LAI, Tim Hing; 315 Shunfu Road, #08-114, Singapore 570315 (SG). LIN, Jing; Block 856B Tampines St. 82, #11-152, Singapore (SG). NG, Lian Seng; Block 540, Serangoon North Avenue 4 #09-103, Singapore 550540 (SG). TAN, Soon Guan; 556 Yishun Avenue 6, #09-11, Singapore 768964 (SG).
- (74) **Agent:** SIM, Charlie; Axis Intellectual Capital PTE LTD., 1 Pemimpin Drive, #12-07, One Pemimpin, Singapore 576151 (SG).
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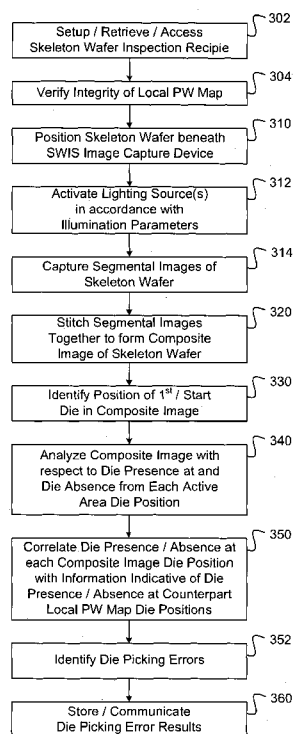
(54) **Title:** SYSTEMS AND METHODS FOR AUTOMATICALLY VERIFYING CORRECT DIE REMOVAL FROM FILM FRAMES

FIG. 9

(57) **Abstract:** A skeleton wafer inspection system includes an expansion table displaceable relative to a camera configured for capturing segmental images of a skeleton wafer on a film frame. During segmental image capture, illumination is directed to the top and/or bottom of the film frame. Segmental images are digitally stitched together to produce a composite image, which can be processed to identify die presence or absence therein at active area die positions having counterpart die positions in a process wafer map. A composite image of a diced wafer on a film frame can also be generated, and used as a navigation aid or guide during die sort operations, or to verify whether a die sort apparatus has correctly detected a reference die prior to die sort operations. A composite image of a skeleton wafer can similarly be generated for use as a navigation aid or guide for film frame repopulation operations.



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